

## Data sheet Product ICK BGA 10 x 10

Heatsinks and active heatsinks for processors>Heatsinks for BGAs  
10 x 10 x 6 mm, for IC design BGA and others

- particularly suited for **Ball Grid Arrays**
- heatsink dimensions match the respective BGA-type
- can be glued directly on the BGA component
- double-sided adhesive thermal conductive foil **WLF ...**
- **surface:** black anodised

### Features

way of fixation:	<ul style="list-style-type: none"> <li>• therm. conductive foil</li> <li>• therm. cond. adhesive</li> </ul>
socket:	<b>universal</b>
suitable for processor type:	<b>universal</b>
width:	<b>10 mm</b>
height:	<b>6 mm</b>
plate thickness:	<b>1.8 mm</b>
length:	<b>10 mm</b>
thermal resistance:	<b>32 - 10 K/W</b>
dissipation loss:	<b>1.8 W</b>
surface:	<b>black anodised</b>

### Technical Drawing

